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(71) Applicants (*for all designated States except US*): **MATSUSHITA ELECTRIC WORKS, LTD.** [JP/JP]; 1048, Oaza-Kadoma, Kadoma-shi, Osaka, 5718686 (JP). **SUMITOMO CHEMICAL COMPANY, LIMITED** [JP/JP]; 27-1, Shinkawa 2-chome, Chuo-ku, Tokyo, 1048260 (JP).

(72) Inventors; and

(75) Inventors/Applicants (*for US only*): **IKEGAWA, Naoto** [JP/JP]; c/o Matsushita Electric Works, Ltd., 1048, Oaza-Kadoma, Kadoma-shi, Osaka 5718686 (JP). **OKAMOTO, Satoshi** [JP/JP]; c/o Sumitomo Chemical Company, Limited, 6, Kitahara, Tsukuba-shi, Ibaraki 3003294 (JP). **KATAGIRI, Shiro** [JP/JP]; c/o Sumitomo Chemical Company, Limited, 6, Kitahara, Tsukuba-shi, Ibaraki 3003294 (JP).

(74) Agents: **NISHIKAWA, Yoshikiyo** et al.; Hokuto Patent Attorneys Office Umeda-Daiichiseimei Bldg. 5th Floor, 12-17, Umeda 1-chome, Kita-ku, Osaka-shi, Osaka 5300001 (JP).

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(54) Title: RESIN MOLDED ARTICLE WITH REDUCED DIELECTRIC LOSS TANGENT AND PRODUCTION METHOD THEREFOR

(57) Abstract: A resin molded article having a reduced dielectric loss tangent is provided. This resin molded article is obtained by performing a heat treatment to a resin composition comprising a liquid-crystalline polyester and an epoxy-group containing ethylene copolymer at a temperature lower than a flow-beginning temperature of the liquid-crystalline polyester, preferably at a temperature between a lower limit temperature calculated by subtracting 120°C from the flow-beginning temperature and an upper limit temperature calculated by subtracting 20°C from the flow-beginning temperature. This resin molded article has a smaller dielectric loss tangent than the resin molded article obtained from the resin composition without the heat treatment.



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